27th Annual
IEEE High Performance Extreme Computing Virtual Conference
25 - 29 September 2023

CALL FOR PAPERS

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The IEEE High Performance Extreme Computing Conference (HPEC '23) will be held virtually 25 – 29 September 2023. The HPEC charter is to be the premier conference in the world on the confluence of HPC and Embedded Computing.

The technical committee seeks new presentations that clearly describe advances in high performance extreme computing technologies, emphasizing one or more of the following topics:

- AI / Machine Learning
- Graph Analytics & Network Science
- Advanced Multicore Software Technologies
- Advanced Processor Architectures
- Automated Design Tools
- Big Data & Distributed Computing
- Big Data Meets Big Compute
- Case Studies & Benchmarking of Applications
- Cloud HPEC
- Computing Technologies for Challenging Form Factors
- ASIC & FPGA Advances

- Quantum and Non-Deterministic Computing
- Data Intensive Computing
- Digital Front Ends
- Fault-Tolerant Computing
- Embedded Cloud Computing
- General Purpose GPU Computing
- High Performance Data Analysis
- Interactive and Real-Time Supercomputing
- Mapping & Scheduling of Parallel & Real-Time Applications
- New Application Frontiers
- Open System Architectures
- Cyber Analysis and Secure Computing

HPEC accepts two types of submissions:	**IMPORTANT DATES**:
1. Full papers (up to 6 pages, references not included. Additional pages can be purchased for $200/page). 2. Extended abstracts (up to 2 pages, references included).	Submission Deadline: **JUL 14, 2023** Notification of Acceptance: **AUG 29, 2023** Camera Ready Deadline: **SEP 14, 2023**

Submissions to HPEC '23 will be accepted through the CMT submission site at:
https://cmt3.research.microsoft.com/HPEC2023/

Preference will be given to papers with strong, quantitative results, demonstrating novel approaches or describing high quality prototypes. Authors of full papers can mark their preference for a poster display or an oral presentation. Presenters who wish to have hardware demonstrations are encouraged to mark their preference for a poster display. Accepted extended abstracts will be displayed as posters. Papers can be declared "student paper" if the first author was a student when doing the presented work and will be eligible for the "IEEE HPEC Best Student Paper Award." Papers should not be anonymized. All paper and extended abstract submissions need to use the approved IEEE templates. Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements. All other accepted submissions and extended abstracts are published on ieee-hpec.org.

Vendors are encouraged to sign up for vendor booths. This will allow vendors to present their HPEC technologies in an interactive atmosphere suitable for product demonstration and promotion. We welcome input (hpec@ieee-hpec.org) on tutorials, invited talks, special sessions, peer reviewed presentations, and vendor demos. Instructions for submitting will be posted on the conference web site shortly.

IEEE-HPEC.org